

## C1206C759B2TACTU

Aliases (C1206C759B2TAC7800)

SMD Comm X8G HT150C, Ceramic, 7.5 pF, +/-0.1 pF, 200 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1206, 1.5 mm



General Information			
Series	SMD Comm X8G HT150C		
Style	SMD Chip		
Description	SMD, MLCC, High Temperature, Ultra-Stable		
Features	High Temperature, Ultra-Stable		
RoHS	Yes		
Termination	Tin		
Marking	No		
AEC-Q200	No		
Typical Component Weight	15 mg		
Shelf Life	78 Weeks		
MSL	1		

Dimensions		
Chip Size	1206	
L	3.2mm +/-0.2mm	
W	1.6mm +/-0.2mm	
Т	0.78mm +/-0.10mm	
S	1.5mm MIN	
В	0.5mm +/-0.25mm	

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Packaging Specifications	

4000

Packaging

Packaging Quantity

T&R, 180mm, Plastic Tape

Specifications		
Capacitance	7.5 pF	
Measurement Condition	1 MHz 1.0Vrms	
Tolerance	+/-0.1 pF	
Voltage DC	200 VDC	
Dielectric Withstanding Voltage	500 VDC	
Temperature Range	-55/+150°C	
Temp. Coefficient	X8G	
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MegaHz 1.0Vrms	
Dissipation Factor	0.1% 1 MHz 1.0Vrms	
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours	
Insulation Resistance	100 GOhms	

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